

ABSTRACT OF THE DISCLOSURE

A semiconductor device package and method of fabricating same. The package includes a lead frame having a die paddle and a plurality of lead fingers. A first semiconductor die exhibiting a first size is adhered to the die paddle and is electrically coupled with one or more of the plurality of lead fingers. A second semiconductor die exhibiting a second size, different from the first size, is also adhered to the die paddle and is electrically coupled with one or more of the plurality of lead fingers. The first semiconductor die and the second semiconductor die each exhibit circuitry which is substantially identical in function. In one embodiment the first semiconductor die may be adhered to a first side of the die paddle while the second semiconductor die is adhered to an opposing side of the die paddle.

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